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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	M16C/60
Core Size	16-Bit
Speed	32MHz
Connectivity	EBI/EMI, I ² C, SIO, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	85
Program Memory Size	384KB (384K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	31K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 26x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LFQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f3650kcncfb-v0

Table 1.3 Specifications for the 100-Pin Package (1/2)

Item	Function	Description
CPU	Central processing unit	M16C/60 Series core (multiplier: 16 bit × 16 bit → 32 bit, multiply and accumulate instruction: 16 bit × 16 bit + 32 bit → 32 bit) • Number of basic instructions: 91 • Minimum instruction execution time: 31.25 ns ($f(\text{BCLK}) = 32 \text{ MHz}$, $\text{VCC1} = \text{VCC2} = 2.7 \text{ to } 5.5 \text{ V}$) • Operating modes: Single-chip, memory expansion, and microprocessor
Memory	ROM, RAM, data flash	See Table 1.5 "Product List (N-Version)" to Table 1.6 "Product List (D-Version)".
Voltage Detection	Voltage detector	• Power-on reset • 3 voltage detection points (detection level of voltage detection 0 and 1 selectable)
Clock	Clock generator	• 5 circuits: Main clock, sub clock, low-speed on-chip oscillator (125 kHz), high-speed on-chip oscillator (40 MHz ±5%), PLL frequency synthesizer • Oscillation stop detection: Main clock oscillation stop/restart detection function • Frequency divider circuit: Divide ratio selectable from 1, 2, 4, 8, and 16 • Power saving features: Wait mode, stop mode • Real-time clock
External Bus Expansion	Bus memory expansion	• Address space: 1 MB • External bus interface: 0 to 8 waits inserted, 4 chip select outputs, memory area expansion function (expandable to 4 MB), 3 V and 5 V interfaces • Bus format: Separate bus or multiplexed bus selectable, data bus width selectable (8 or 16 bits), number of address buses selectable (12, 16, or 20)
I/O Ports	Programmable I/O ports	• CMOS I/O ports: 85 (selectable pull-up resistors) • N-channel open drain ports: 3
Interrupts		• Interrupt vectors: 70 • External interrupt inputs: 13 ($\overline{\text{NMI}}$, $\overline{\text{INT}} \times 8$, key input × 4) • Interrupt priority levels: 7
Watchdog Timer		15-bit timer × 1 (with prescaler) Automatic reset start function selectable
DMA	DMAC	• 4 channels, cycle steal mode • Trigger sources: 43 • Transfer modes: 2 (single transfer, repeat transfer)

Table 1.7 Pin Names for the 128-Pin Package (1/3)

Pin No.	Control Pin	Port	I/O Pin for Peripheral Function				Bus Control Pin
			Interrupt	Timer	Serial interface	A/D converter, D/A converter	
1	VREF						
2	AVCC						
3		P9_7			SIN4	ADTRG	
4		P9_6			SOUT4	ANEX1	
5		P9_5			CLK4	ANEX0	
6		P9_4		TB4IN/PWM1		DA1	
7		P9_3		TB3IN/PWM0		DA0	
8		P9_2		TB2IN/PMC0	SOUT3		
9		P9_1		TB1IN/PMC1	SIN3		
10		P9_0		TB0IN	CLK3		
11		P14_1					
12		P14_0					
13	BYTE						
14	CNVSS						
15	XCIN	P8_7					
16	XCOUT	P8_6					
17	RESET						
18	XOUT						
19	VSS						
20	XIN						
21	VCC1						
22		P8_5	NMI	SD	CEC		
23		P8_4	INT2	ZP			
24		P8_3	INT1				
25		P8_2	INT0				
26		P8_1		TA4IN/U	CTS5/RTS5		
27		P8_0		TA4OUT/U	RXD5/SCL5		
28		P7_7		TA3IN	CLK5		
29		P7_6		TA3OUT	TXD5/SDA5		
30		P7_5		TA2IN/W			
31		P7_4		TA2OUT/W			
32		P7_3		TA1IN/V	CTS2/RTS2		
33		P7_2		TA1OUT/V	CLK2		
34		P7_1		TA0IN/TB5IN	RXD2/SCL2/SCLMM		
35		P7_0		TA0OUT	TXD2/SDA2/SDAMM		
36		P6_7			TXD1/SDA1		
37	VCC1						
38		P6_6			RXD1/SCL1		
39	VSS						
40		P6_5			CLK1		
41		P6_4			CTS1/RTS1/CTS0/CLKS1		
42		P6_3			TXD0/SDA0		
43		P6_2			RXD0/SCL0		
44		P6_1			CLK0		
45		P6_0		RTCOU	CTS0/RTS0		
46		P13_7					
47		P13_6					
48		P13_5					
49		P13_4					
50	CLKOUT	P5_7					RDY

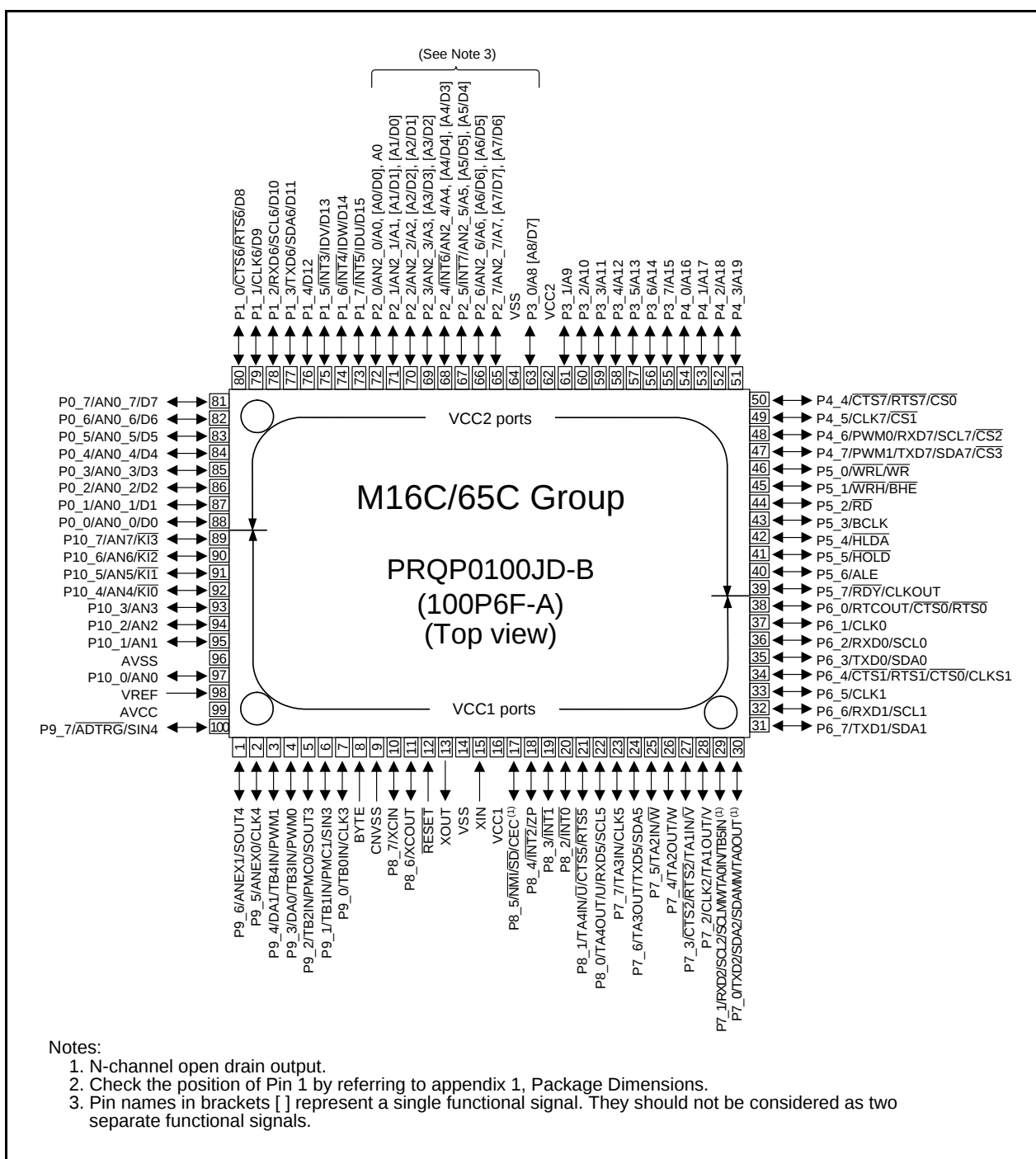


Figure 1.6 Pin Assignment for the 100-Pin Package

Table 1.16 Pin Functions for the 100-Pin Package (2/3)

Signal Name	Pin Name	I/O	Power Supply	Description
Main clock input	XIN	I	VCC1	I/O for the main clock oscillator. Connect a ceramic resonator or crystal between pins XIN and XOUT. ⁽¹⁾ Input an external clock to XIN pin and leave XOUT pin open.
Main clock output	XOUT	O	VCC1	
Sub clock input	XCIN	I	VCC1	I/O for a sub clock oscillator. Connect a crystal between XCIN pin and XCOUT pin. ⁽¹⁾ Input an external clock to XCIN pin and leave XCOUT pin open.
Sub clock output	XCOUT	O	VCC1	
BCLK output	BCLK	O	VCC2	Outputs the BCLK signal.
Clock output	CLKOUT	O	VCC2	Outputs a clock with the same frequency as f _C , f ₁ , f ₈ , or f ₃₂ .
$\overline{\text{INT}}$ interrupt input	$\overline{\text{INT0}}$ to $\overline{\text{INT2}}$	I	VCC1	Input for the $\overline{\text{INT}}$ interrupt.
	$\overline{\text{INT3}}$ to $\overline{\text{INT7}}$	I	VCC2	
$\overline{\text{NMI}}$ interrupt input	$\overline{\text{NMI}}$	I	VCC1	Input for the $\overline{\text{NMI}}$ interrupt.
Key input interrupt input	$\overline{\text{KI0}}$ to $\overline{\text{KI3}}$	I	VCC1	Input for the key input interrupt.
Timer A	TA0OUT to TA4OUT	I/O	VCC1	I/O for timers A0 to A4 (TA0OUT is N-channel open drain output).
	TA0IN to TA4IN	I	VCC1	Input for timers A0 to A4.
	ZP	I	VCC1	Input for Z-phase.
Timer B	TB0IN to TB5IN	I	VCC1	Input for timers B0 to B5.
Three-phase motor control timer	U, $\overline{\text{U}}$, V, $\overline{\text{V}}$, W, $\overline{\text{W}}$	O	VCC1	Output for the three-phase motor control timer.
	$\overline{\text{SD}}$	I	VCC1	Forced cutoff input.
	IDU, IDV, IDW	I	VCC2	Input for the position data.
Real-time clock output	RTCOUT	O	VCC1	Output for the real-time clock.
PWM output	PWM0, PWM1	O	VCC1, VCC2	PWM output.
Remote control signal receiver input	PMC0, PMC1	I	VCC1	Input for the remote control signal receiver.
Serial interface UART0 to UART2, UART5 to UART7	CTS0 to CTS2, CTS5	I	VCC1	Input pins to control data transmission.
	CTS6, CTS7	I	VCC2	
	RTS0 to RTS2, RTS5	O	VCC1	Output pins to control data reception.
	RTS6, RTS7	O	VCC2	
	CLK0 to CLK2, CLK5	I/O	VCC1	Transmit/receive clock I/O.
	CLK6, CLK7	I/O	VCC2	
	RXD0 to RXD2, RXD5	I	VCC1	Serial data input.
	RXD6, RXD7	I	VCC2	
	TXD0 to TXD2, TXD5	O	VCC1	Serial data output. ⁽²⁾
	TXD6, TXD7	O	VCC2	
	CLKS1	O	VCC1	Output for the transmit/receive clock multiple-pin output function.

Notes:

- Contact the manufacturer of crystal/ceramic resonator regarding the oscillation characteristics.
- TXD2, SDA2, and SCL2 are N-channel open drain output pins. TXDi (i = 0, 1, 5 to 7), SDAi, and SCLi can be selected as CMOS output pins or N-channel open drain output pins.

Table 4.4 SFR Information (4) ⁽¹⁾

Address	Register	Symbol	Reset Value
0060h			
0061h			
0062h			
0063h			
0064h			
0065h			
0066h			
0067h			
0068h			
0069h	DMA2 Interrupt Control Register	DM2IC	XXXX X000b
006Ah	DMA3 Interrupt Control Register	DM3IC	XXXX X000b
006Bh	UART5 Bus Collision Detection Interrupt Control Register CEC1 Interrupt Control Register	U5BCNIC CEC1IC	XXXX X000b
006Ch	UART5 Transmit Interrupt Control Register CEC2 Interrupt Control Register	S5TIC CEC2IC	XXXX X000b
006Dh	UART5 Receive Interrupt Control Register	S5RIC	XXXX X000b
006Eh	UART6 Bus Collision Detection Interrupt Control Register Real-Time Clock Periodic Interrupt Control Register	U6BCNIC RTCTIC	XXXX X000b
006Fh	UART6 Transmit Interrupt Control Register Real-Time Clock Compare Interrupt Control Register	S6TIC RTCCIC	XXXX X000b
0070h	UART6 Receive Interrupt Control Register	S6RIC	XXXX X000b
0071h	UART7 Bus Collision Detection Interrupt Control Register Remote Control Signal Receiver 0 Interrupt Control Register	U7BCNIC PMC0IC	XXXX X000b
0072h	UART7 Transmit Interrupt Control Register Remote Control Signal Receiver 1 Interrupt Control Register	S7TIC PMC1IC	XXXX X000b
0073h	UART7 Receive Interrupt Control Register	S7RIC	XXXX X000b
0074h			
0075h			
0076h			
0077h			
0078h			
0079h			
007Ah			
007Bh	I2C-bus Interface Interrupt Control Register	IICIC	XXXX X000b
007Ch	SCL/SDA Interrupt Control Register	SCLDAIC	XXXX X000b
007Dh			
007Eh			
007Fh			
0080h to 017Fh			

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

Table 4.7 SFR Information (7) ⁽¹⁾

Address	Register	Symbol	Reset Value
01E0h	Timer B3-1 Register	TB31	XXh
01E1h			XXh
01E2h			XXh
01E3h	Timer B4-1 Register	TB41	XXh
01E4h			XXh
01E5h	Timer B5-1 Register	TB51	XXh
01E6h			XXh
01E6h	Pulse Period/Pulse Width Measurement Mode Function Select Register 2	PPWFS2	XXXX X000b
01E7h			
01E8h	Timer B Count Source Select Register 2	TBCS2	00h
01E9h	Timer B Count Source Select Register 3	TBCS3	X0h
01EAh			
01EBh			
01ECh			
01EDh			
01EEh			
01EFh			
01F0h	PMC0 Function Select Register 0	PMC0CON0	00h
01F1h	PMC0 Function Select Register 1	PMC0CON1	00XX 0000b
01F2h	PMC0 Function Select Register 2	PMC0CON2	0000 00X0b
01F3h	PMC0 Function Select Register 3	PMC0CON3	00h
01F4h	PMC0 Status Register	PMC0STS	00h
01F5h	PMC0 Interrupt Source Select Register	PMC0INT	00h
01F6h	PMC0 Compare Control Register	PMC0CPC	XXX0 X000b
01F7h	PMC0 Compare Data Register	PMC0CPD	00h
01F8h	PMC1 Function Select Register 0	PMC1CON0	XXX0 X000b
01F9h	PMC1 Function Select Register 1	PMC1CON1	XXXX 0X00b
01FAh	PMC1 Function Select Register 2	PMC1CON2	0000 00X0b
01FBh	PMC1 Function Select Register 3	PMC1CON3	00h
01FCh	PMC1 Status Register	PMC1STS	X000 X00Xb
01FDh	PMC1 Interrupt Source Select Register	PMC1INT	X000 X00Xb
01FEh			
01FFh			
0200h			
0201h			
0202h			
0203h			
0204h			
0205h	Interrupt Source Select Register 3	IFSR3A	00h
0206h	Interrupt Source Select Register 2	IFSR2A	00h
0207h	Interrupt Source Select Register	IFSR	00h
0208h			
0209h			
020Ah			
020Bh			
020Ch			
020Dh			
020Eh	Address Match Interrupt Enable Register	AIER	XXXX XX00b
020Fh	Address Match Interrupt Enable Register 2	AIER2	XXXX XX00b

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

Table 4.17 SFR Information (17) ⁽¹⁾

Address	Register	Symbol	Reset Value
03F0h	Port P8 Register	P8	XXh
03F1h	Port P9 Register	P9	XXh
03F2h	Port P8 Direction Register	PD8	00h
03F3h	Port P9 Direction Register	PD9	00h
03F4h	Port P10 Register	P10	XXh
03F5h	Port P11 Register	P11	XXh
03F6h	Port P10 Direction Register	PD10	00h
03F7h	Port P11 Direction Register	PD11	00h
03F8h	Port P12 Register	P12	XXh
03F9h	Port P13 Register	P13	XXh
03FAh	Port P12 Direction Register	PD12	00h
03FBh	Port P13 Direction Register	PD13	00h
03FCh	Port P14 Register	P14	XXh
03FDh			
03FEh	Port P14 Direction Register	PD14	XXXX XX00b
03FFh			

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

5. Electrical Characteristics

5.1 Electrical Characteristics (Common to 3 V and 5 V)

5.1.1 Absolute Maximum Rating

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter		Condition	Rated Value	Unit
V _{CC1}	Supply voltage		V _{CC1} = AV _{CC}	−0.3 to 6.5	V
V _{CC2}	Supply voltage		V _{CC1} = AV _{CC}	−0.3 to V _{CC1} + 0.1 ⁽¹⁾	V
AV _{CC}	Analog supply voltage		V _{CC1} = AV _{CC}	−0.3 to 6.5	V
V _{REF}	Analog reference voltage		V _{CC1} = AV _{CC}	−0.3 to V _{CC1} + 0.1 ⁽¹⁾	V
V _I	Input voltage	RESET, CNVSS, BYTE, P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P14_0, P14_1 XIN		−0.3 to V _{CC1} + 0.3 ⁽¹⁾	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P12_0 to P12_7, P13_0 to P13_7		−0.3 to V _{CC2} + 0.3 ⁽¹⁾	V
		P7_0, P7_1, P8_5		−0.3 to 6.5	V
V _O	Output voltage	P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P14_0, P14_1 XOUT		−0.3 to V _{CC1} + 0.3 ⁽¹⁾	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P12_0 to P12_7, P13_0 to P13_7		−0.3 to V _{CC2} + 0.3 ⁽¹⁾	V
		P7_0, P7_1, P8_5		−0.3 to 6.5	V
P _d	Power consumption		−40°C < T _{opr} ≤ 85°C	300	mW
T _{opr}	Operating temperature	When the MCU is operating		−20 to 85/−40 to 85	°C
		Flash program erase	Program area	0 to 60	
			Data area	−20 to 85/−40 to 85	
T _{stg}	Storage temperature			−65 to 150	°C

Note:

1. Maximum value is 6.5 V.

5.1.3 A/D Conversion Characteristics

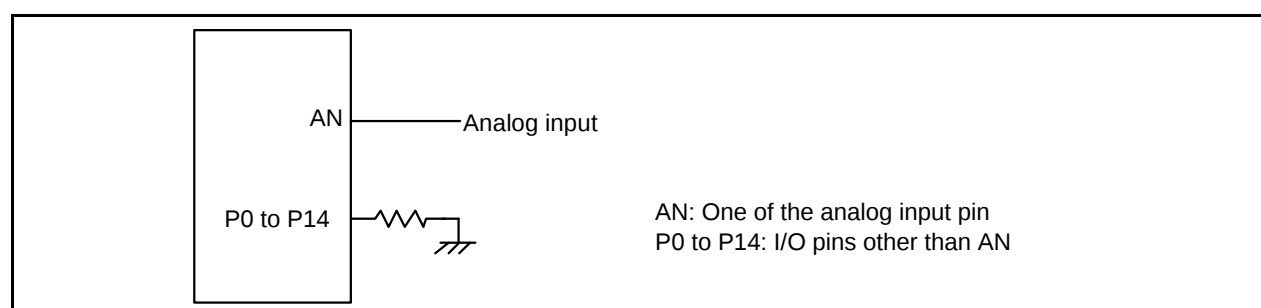
Table 5.5 A/D Conversion Characteristics (1/2) ⁽¹⁾

$V_{CC1} = AV_{CC} = 3.0 \text{ to } 5.5 \text{ V} \geq V_{CC2} \geq V_{REF}$, $V_{SS} = AV_{SS} = 0 \text{ V}$ at $T_{opr} = -20^\circ\text{C}$ to 85°C / -40°C to 85°C unless otherwise specified.

Symbol	Parameter		Measuring Condition		Standard			Unit
					Min.	Typ.	Max.	
-	Resolution		$AV_{CC} = V_{CC1} \geq V_{CC2} \geq V_{REF}$				10	Bits
I_{NL}	Integral non-linearity error	10 bits	$V_{CC1} = 5.0 \text{ V}$	AN0 to AN7 input, AN0_0 to AN0_7 input, AN2_0 to AN2_7 input, ANEX0, ANEX1 input (Note 2)			± 3	LSB
			$V_{CC1} = 3.3 \text{ V}$	AN0 to AN7 input, AN0_0 to AN0_7 input, AN2_0 to AN2_7 input, ANEX0, ANEX1 input (Note 2)			± 3	LSB
			$V_{CC1} = 3.0 \text{ V}$	AN0 to AN7 input, AN0_0 to AN0_7 input, AN2_0 to AN2_7 input, ANEX0, ANEX1 input (Note 2)			± 3	LSB
-	Absolute accuracy	10 bits	$V_{CC1} = 5.0 \text{ V}$	AN0 to AN7 input, AN0_0 to AN0_7 input, AN2_0 to AN2_7 input, ANEX0, ANEX1 input (Note 2)			± 3	LSB
			$V_{CC1} = 3.3 \text{ V}$	AN0 to AN7 input, AN0_0 to AN0_7 input, AN2_0 to AN2_7 input, ANEX0, ANEX1 input (Note 2)			± 3	LSB
			$V_{CC1} = 3.0 \text{ V}$	AN0 to AN7 input, AN0_0 to AN0_7 input, AN2_0 to AN2_7 input, ANEX0, ANEX1 input (Note 2)			± 3	LSB

Notes:

1. Use when $AV_{CC} = V_{CC1}$.
2. Flash memory rewrite disabled. Except for the analog input pin, set the pins to be measured as input ports and connect them to V_{SS} . See Figure 5.2 "A/D Accuracy Measure Circuit".


Figure 5.2 A/D Accuracy Measure Circuit

5.1.7 Oscillator Electrical Characteristics

Table 5.16 40 MHz On-Chip Oscillator Electrical Characteristics (1/2)

$V_{CC1} = 2.7$ to 5.5 V, $T_{opr} = -20^{\circ}\text{C}$ to $85^{\circ}\text{C}/-40^{\circ}\text{C}$ to 85°C , unless otherwise specified.

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
f_{OCO40M}	40 MHz on-chip oscillator frequency	Average frequency in a 10 ms period	38	40	42	MHz
$tsu(f_{OCO40M})$	Wait time until 40 MHz on-chip oscillator stabilizes				2	ms

Table 5.17 125 kHz On-Chip Oscillator Electrical Characteristics

$V_{CC1} = 2.7$ to 5.5 V, $T_{opr} = -20^{\circ}\text{C}$ to $85^{\circ}\text{C}/-40^{\circ}\text{C}$ to 85°C , unless otherwise specified.

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
f_{OCO-S}	125 kHz on-chip oscillator frequency	Average frequency in a 10 ms period	100	125	150	kHz
$tsu(f_{OCO-S})$	Wait time until 125 kHz on-chip oscillator stabilizes				20	μs

$$V_{CC1} = V_{CC2} = 5 \text{ V}$$

Switching Characteristics

($V_{CC1} = V_{CC2} = 5 \text{ V}$, $V_{SS} = 0 \text{ V}$, at $T_{opr} = -20^{\circ}\text{C}$ to $85^{\circ}\text{C}/-40^{\circ}\text{C}$ to 85°C unless otherwise specified)

5.2.4.2 In 1 to 3 Waits Setting and When Accessing External Area**Table 5.37 Memory Expansion Mode and Microprocessor Mode (in 1 to 3 Waits Setting and When Accessing External Area)**

Symbol	Parameter	Measuring Condition	Standard		Unit
			Min.	Max.	
$t_{d(BCLK-AD)}$	Address output delay time	See Figure 5.14		25	ns
$t_{h(BCLK-AD)}$	Address output hold time (in relation to BCLK)		0		ns
$t_{h(RD-AD)}$	Address output hold time (in relation to RD)		0		ns
$t_{h(WR-AD)}$	Address output hold time (in relation to WR)		(Note 2)		ns
$t_{d(BCLK-CS)}$	Chip select output delay time			25	ns
$t_{h(BCLK-CS)}$	Chip select output hold time (in relation to BCLK)		0		ns
$t_{d(BCLK-ALE)}$	ALE signal output delay time			15	ns
$t_{h(BCLK-ALE)}$	ALE signal output hold time		-4		ns
$t_{d(BCLK-RD)}$	RD signal output delay time			25	ns
$t_{h(BCLK-RD)}$	RD signal output hold time		0		ns
$t_{d(BCLK-WR)}$	WR signal output delay time			25	ns
$t_{h(BCLK-WR)}$	WR signal output hold time		0		ns
$t_{d(BCLK-DB)}$	Data output delay time (in relation to BCLK)			40	ns
$t_{d(DB-WR)}$	Data output delay time (in relation to WR)		(Note 1)		ns
$t_{h(WR-DB)}$	Data output hold time (in relation to WR) ⁽³⁾		(Note 4)		ns

Notes:

1. Calculated according to the BCLK frequency as follows:

$$\frac{(n-0.5) \times 10^9}{f_{(BCLK)}} - 40 [ns] \quad \begin{array}{l} n \text{ is 1 for 1 wait setting, 2 for 2 waits setting and 3 for 3 waits setting.} \\ \text{When } n = 1, f_{(BCLK)} \text{ is 12.5 MHz or less.} \end{array}$$

2. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f_{(BCLK)}} - 10 [ns]$$

3. This standard value shows the timing when the output is off, and does not show hold time of data bus.
Hold time of data bus varies with capacitor volume and pull-up (pull-down) resistance value.

Hold time of data bus is expressed in

$$t = -CR \times \ln(1 - V_{OL}/V_{CC2})$$

by a circuit of the right figure.

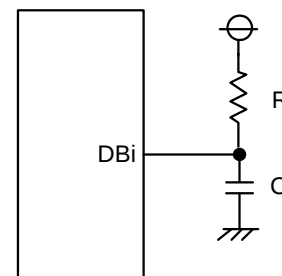
For example, when $V_{OL} = 0.2V_{CC2}$, $C = 30 \text{ pF}$, $R = 1 \text{ k}\Omega$, hold time of output low level is

$$t = -30 \text{ pF} \times 1 \text{ k}\Omega \times \ln(1 - 0.2V_{CC2}/V_{CC2}) = 6.7 \text{ ns.}$$

4. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f_{(BCLK)}} - 20 [ns]$$

Hold time is equal to or less than 0 ns when the BCLK frequency exceeds 25 MHz.



$$V_{CC1} = V_{CC2} = 5 \text{ V}$$

Switching Characteristics

($V_{CC1} = V_{CC2} = 5 \text{ V}$, $V_{SS} = 0 \text{ V}$, at $T_{opr} = -20^{\circ}\text{C}$ to 85°C / -40°C to 85°C unless otherwise specified)

5.2.4.3 In 2 or 3 Waits Setting, and When Accessing External Area and Using Multiplexed Bus

Table 5.38 Memory Expansion Mode and Microprocessor Mode (in 2 or 3 Waits Setting, and When Accessing External Area and Using Multiplexed Bus) (5)

Symbol	Parameter	Measuring Condition	Standard		Unit
			Min.	Max.	
$t_{d(BCLK-AD)}$	Address output delay time	See Figure 5.14		25	ns
$t_{h(BCLK-AD)}$	Address output hold time (in relation to BCLK)		0		ns
$t_{h(RD-AD)}$	Address output hold time (in relation to RD)		(Note 1)		ns
$t_{h(WR-AD)}$	Address output hold time (in relation to WR)		(Note 1)		ns
$t_{d(BCLK-CS)}$	Chip select output delay time			25	ns
$t_{h(BCLK-CS)}$	Chip select output hold time (in relation to BCLK)		0		ns
$t_{h(RD-CS)}$	Chip select output hold time (in relation to RD)		(Note 1)		ns
$t_{h(WR-CS)}$	Chip select output hold time (in relation to WR)		(Note 1)		ns
$t_{d(BCLK-RD)}$	RD signal output delay time			25	ns
$t_{h(BCLK-RD)}$	RD signal output hold time		0		ns
$t_{d(BCLK-WR)}$	WR signal output delay time			25	ns
$t_{h(BCLK-WR)}$	WR signal output hold time		0		ns
$t_{d(BCLK-DB)}$	Data output delay time (in relation to BCLK)			40	ns
$t_{d(DB-WR)}$	Data output delay time (in relation to WR)		(Note 2)		ns
$t_{h(WR-DB)}$	Data output hold time (in relation to WR)		(Note 6)		ns
$t_{d(BCLK-ALE)}$	ALE signal output delay time (in relation to BCLK)			15	ns
$t_{h(BCLK-ALE)}$	ALE signal output hold time (in relation to BCLK)		-4		ns
$t_{d(AD-ALE)}$	ALE signal output delay time (in relation to Address)		(Note 3)		ns
$t_{h(AD-ALE)}$	ALE signal output hold time (in relation to Address)		(Note 4)		ns
$t_{d(AD-RD)}$	RD signal output delay from the end of address		0		ns
$t_{d(AD-WR)}$	WR signal output delay from the end of address		0		ns
$t_{dz(RD-AD)}$	Address output floating start time			8	ns

Notes:

1. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f_{(BCLK)}} - 10[\text{ns}]$$

2. Calculated according to the BCLK frequency as follows:

$$\frac{(n - 0.5) \times 10^9}{f_{(BCLK)}} - 40[\text{ns}] \quad n \text{ is 2 for 2-wait setting, 3 for 3-wait setting.}$$

3. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f_{(BCLK)}} - 25[\text{ns}]$$

4. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f_{(BCLK)}} - 15[\text{ns}]$$

5. When using multiplex bus, set $f_{(BCLK)}$ 12.5 MHz or less.

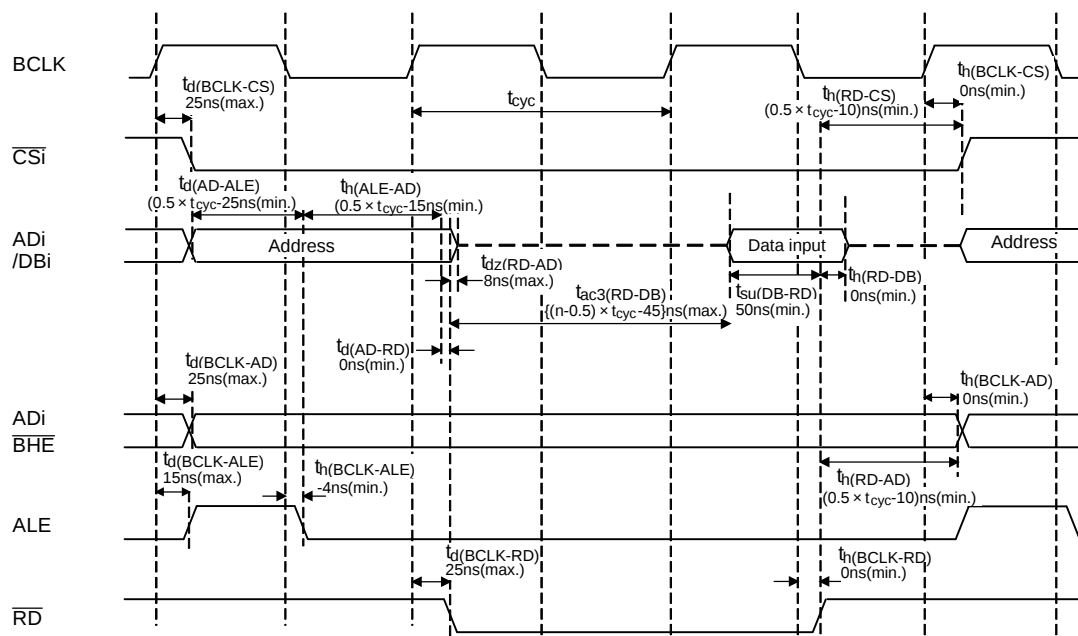
6. Calculated according to the BCLK frequency as follows: $\frac{0.5 \times 10^9}{f_{(BCLK)}} - 20[\text{ns}]$

Memory Expansion Mode and Microprocessor Mode

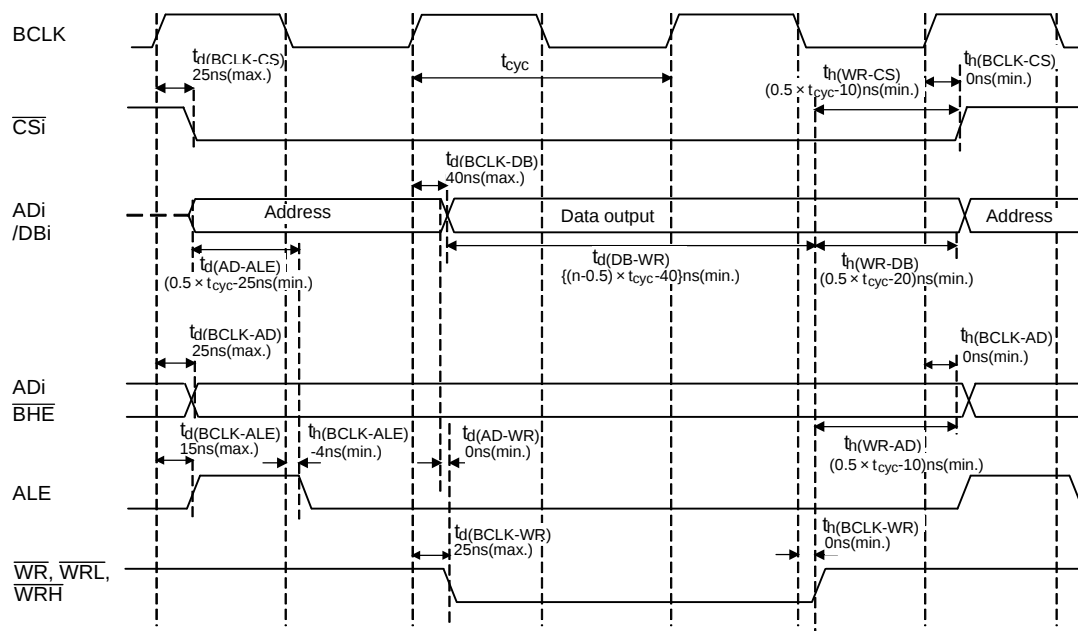
(in 2 or 3 waits setting, and when accessing external area and using multiplexed bus)

$$V_{CC1} = V_{CC2} = 5V$$

Read timing



Write timing



Measuring conditions

- $V_{CC1} = V_{CC2} = 5V$
- Input timing voltage: $V_L = 0.8V$, $V_H = 2.0V$
- Output timing voltage: $V_L = 0.4V$, $V_H = 2.4V$

n: 2 (when 2 waits)
3 (when 3 waits)

Figure 5.17 Timing Diagram

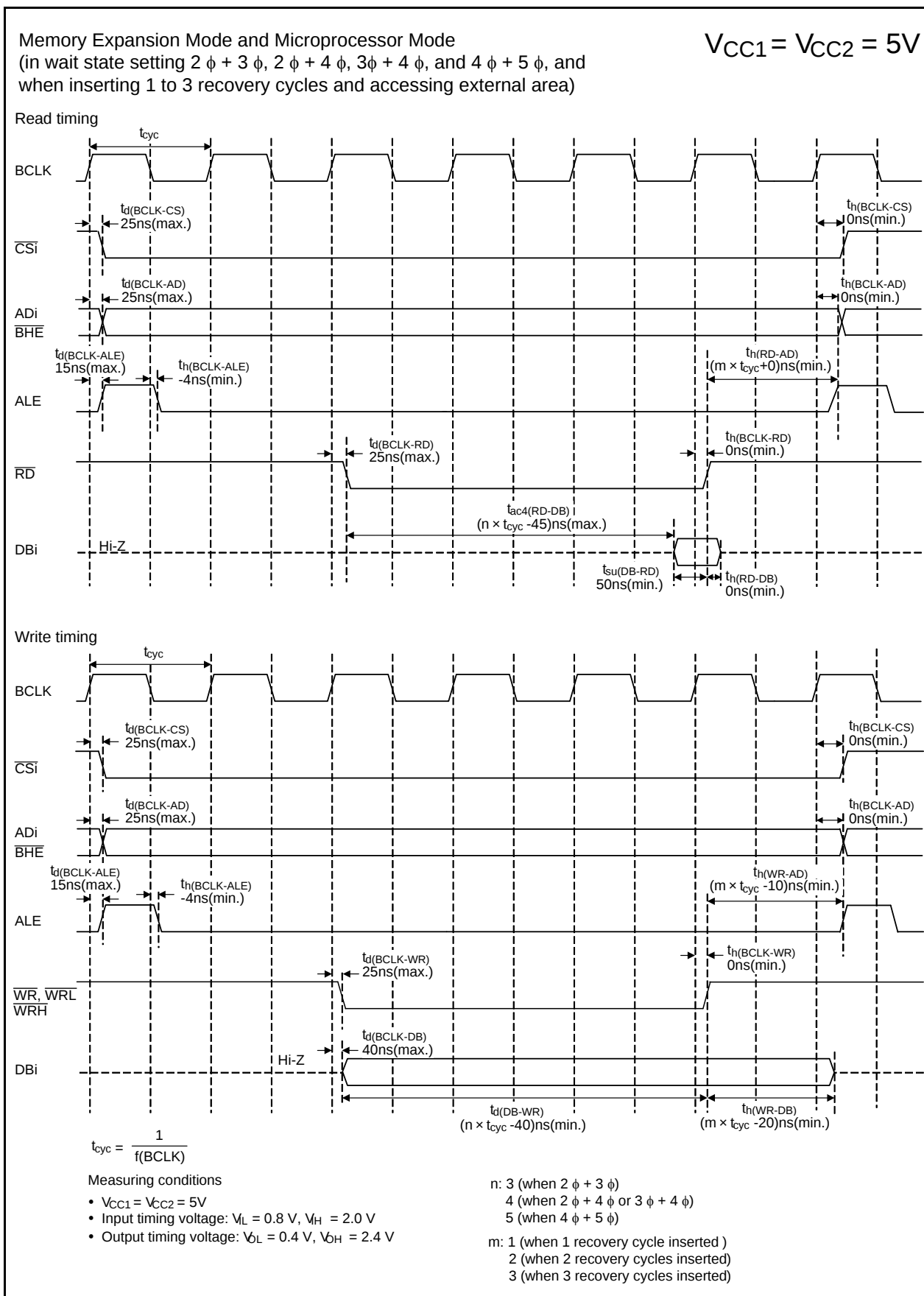


Figure 5.19 Timing Diagram

5.3 Electrical Characteristics ($V_{CC1} = V_{CC2} = 3\text{ V}$)

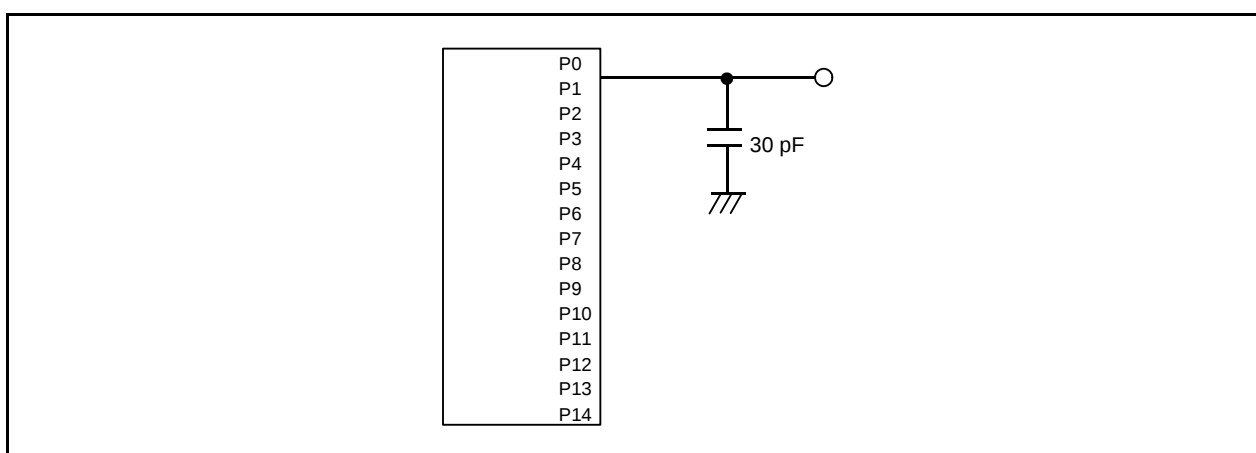
5.3.1 Electrical Characteristics

 $V_{CC1} = V_{CC2} = 3\text{ V}$
Table 5.41 Electrical Characteristics (1) (1)
 $V_{CC1} = V_{CC2} = 2.7\text{ to }3.3\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{opr} = -20^{\circ}\text{C to }85^{\circ}\text{C}/-40^{\circ}\text{C to }85^{\circ}\text{C}$, $f_{(BCLK)} = 32\text{ MHz}$ unless otherwise specified.

Symbol	Parameter		Measuring Condition	Standard			Unit
				Min.	Typ.	Max.	
V_{OH}	High output voltage	P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P14_0, P14_1	$I_{OH} = -1\text{ mA}$	$V_{CC1} - 0.5$		V_{CC1}	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P12_0 to P12_7, P13_0 to P13_7	$I_{OH} = -1\text{ mA}$	$V_{CC2} - 0.5$		V_{CC2}	
V_{OH}	High output voltage XOUT	HIGH POWER	$I_{OH} = -0.1\text{ mA}$	$V_{CC1} - 0.5$		V_{CC1}	V
		LOW POWER	$I_{OH} = -50\text{ }\mu\text{A}$	$V_{CC1} - 0.5$		V_{CC1}	
	High output voltage XCOUT	HIGH POWER	With no load applied		2.6		V
		LOW POWER	With no load applied		2.2		
V_{OL}	Low output voltage	P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P14_0, P14_1	$I_{OL} = 1\text{ mA}$			0.5	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P12_0 to P12_7, P13_0 to P13_7	$I_{OL} = 1\text{ mA}$			0.5	
	CEC		$I_{OL} = 1\text{ mA}$		0	0.5	V
V_{OL}	Low output voltage XOUT	HIGH POWER	$I_{OL} = 0.1\text{ mA}$			0.5	V
		LOW POWER	$I_{OL} = 50\text{ }\mu\text{A}$			0.5	
	Low output voltage XCOUT	HIGH POWER	With no load applied		0		V
		LOW POWER	With no load applied		0		
$V_{T+}-V_{T-}$	Hysteresis	HOLD, RDY, TA0IN to TA4IN, TB0IN to TB5IN, INT0 to INT7, NMI, ADTRG, CTS0 to CTS2, CTS5 to CTS7, SCL0 to SCL2, SCL5 to SCL7, SDA0 to SDA2, SDA5 to SDA7, CLK0 to CLK7, TA0OUT to TA4OUT, K10 to K13, RXD0 to RXD2, RXD5 to RXD7, SIN3, SIN4, $\overline{\text{SD}}$, PMC0, PMC1, SCLMM, SDAMM, ZP, IDU, IDV, IDW		0.2		1.0	V
		CEC		0.2	0.5	1.0	V
		RESET		0.2		1.8	V
I_{IH}	High input current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_7, P13_0 to P13_7, P14_0, P14_1 XIN, RESET, CNVSS, BYTE	$V_I = 3\text{ V}$			4.0	μA
–	Leakage current in powered-off state		CEC	$V_{CC1} = 0\text{ V}$		1.8	μA
I_{IL}	Low input current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_7, P13_0 to P13_7, P14_0, P14_1 XIN, RESET, CNVSS, BYTE	$V_I = 0\text{ V}$			–4.0	μA
R_{PULLUP}	Pull-up resistance	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_7, P13_0 to P13_7, P14_0, P14_1	$V_I = 0\text{ V}$	50	80	150	$\text{k}\Omega$
R_{FXIN}	Feedback resistance XIN				3.0		$\text{M}\Omega$
V_{RAM}	RAM retention voltage		In stop mode	1.8			V

Note:

- When $V_{CC1} \neq V_{CC2}$, refer to 5 V or 3 V standard depending on the voltage.

**Figure 5.29 Ports P0 to P14 Measurement Circuit**

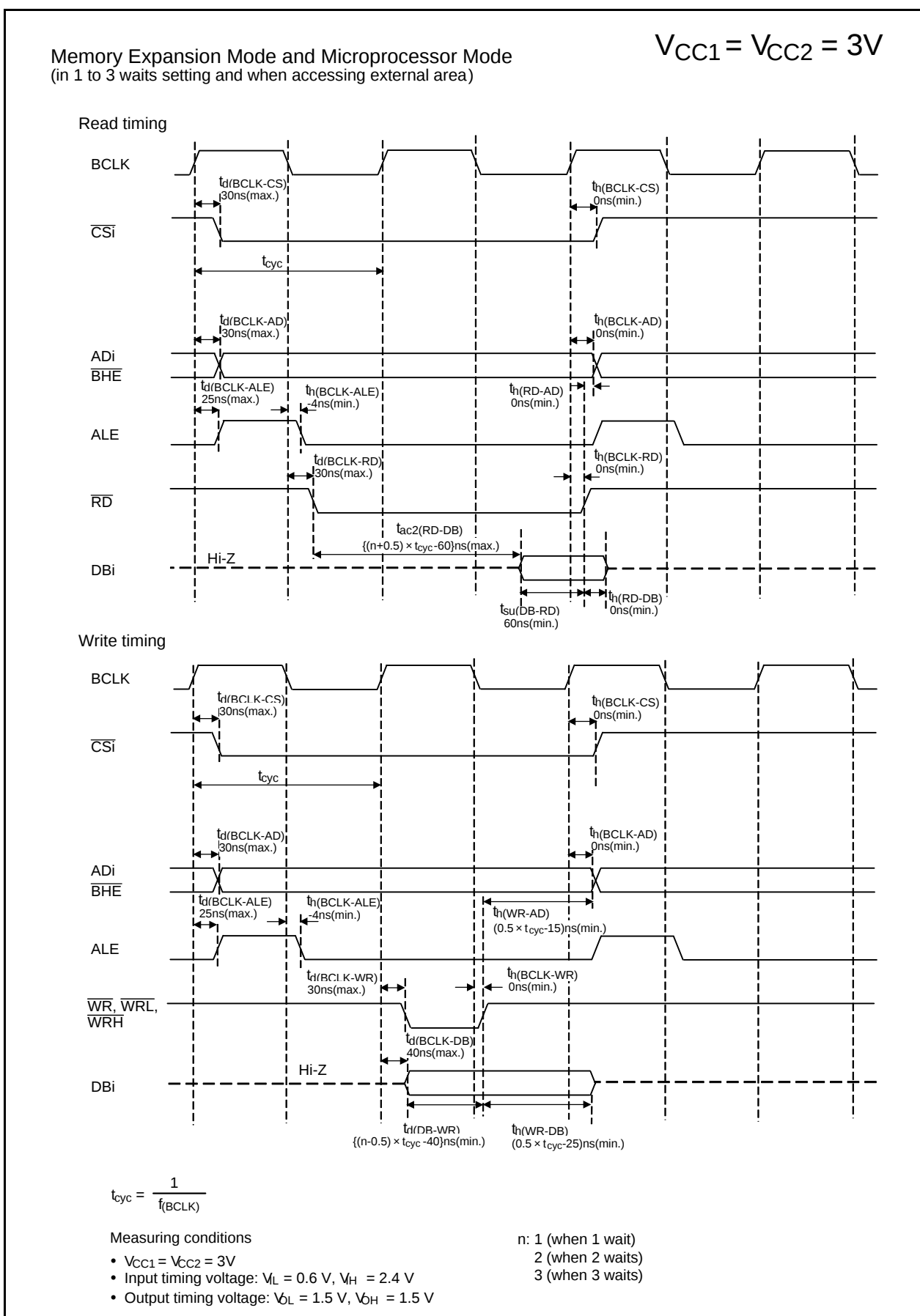


Figure 5.31 Timing Diagram

$$V_{CC1} = V_{CC2} = 3 \text{ V}$$

Switching Characteristics

($V_{CC1} = V_{CC2} = 3 \text{ V}$, $V_{SS} = 0 \text{ V}$, at $T_{opr} = -20^{\circ}\text{C}$ to 85°C / -40°C to 85°C unless otherwise specified)

5.3.4.4 In Wait State Setting $2\phi + 3\phi$, $2\phi + 4\phi$, $3\phi + 4\phi$, and $4\phi + 5\phi$, and When Accessing External Area

Table 5.62 Memory Expansion and Microprocessor Modes (in Wait State Setting $2\phi + 3\phi$, $2\phi + 4\phi$, $3\phi + 4\phi$, and $4\phi + 5\phi$, and When Accessing External Area)

Symbol	Parameter	Measuring Condition	Standard		Unit
			Min.	Max.	
$t_{d(BCLK-AD)}$	Address output delay time	See Figure 5.29		30	ns
$t_{h(BCLK-AD)}$	Address output hold time (in relation to BCLK)		0		ns
$t_{h(RD-AD)}$	Address output hold time (in relation to RD)		0		ns
$t_{h(WR-AD)}$	Address output hold time (in relation to WR)		(Note 2)		ns
$t_{d(BCLK-CS)}$	Chip select output delay time			30	ns
$t_{h(BCLK-CS)}$	Chip select output hold time (in relation to BCLK)		0		ns
$t_{d(BCLK-ALE)}$	ALE signal output delay time			25	ns
$t_{h(BCLK-ALE)}$	ALE signal output hold time		-4		ns
$t_{d(BCLK-RD)}$	RD signal output delay time			30	ns
$t_{h(BCLK-RD)}$	RD signal output hold time		0		ns
$t_{d(BCLK-WR)}$	WR signal output delay time			30	ns
$t_{h(BCLK-WR)}$	WR signal output hold time		0		ns
$t_{d(BCLK-DB)}$	Data output delay time (in relation to BCLK)			40	ns
$t_{d(DB-WR)}$	Data output delay time (in relation to WR)		(Note 1)		ns
$t_{h(WR-DB)}$	Data output hold time (in relation to WR) ⁽³⁾		(Note 4)		ns

Notes:

1. Calculated according to the BCLK frequency as follows:

$$\frac{(n - 0.5) \times 10^9}{f_{(BCLK)}} - 40[ns] \quad n \text{ is 3 for } 2\phi + 3\phi, 4 \text{ for } 2\phi + 4\phi, 4 \text{ for } 3\phi + 4\phi, \text{ and } 5 \text{ for } 4\phi + 5\phi.$$

2. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f_{(BCLK)}} - 15[ns]$$

3. This standard value shows the timing when the output is off, and does not show hold time of data bus.

Hold time of data bus varies with capacitor volume and pull-up (pull-down) resistance value.

Hold time of data bus is expressed in

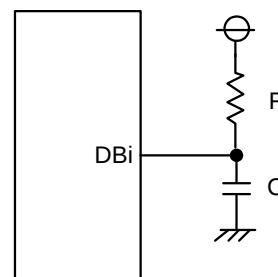
$$t = -CR \times \ln(1 - V_{OL}/V_{CC2})$$

by a circuit of the right figure.

For example, when $V_{OL} = 0.2V_{CC2}$, $C = 30 \text{ pF}$, $R = 1 \text{ k}\Omega$,

hold time of output low level is

$$t = -30 \text{ pF} \times 1 \text{ k}\Omega \times \ln(1 - 0.2V_{CC2}/V_{CC2}) = 6.7 \text{ ns}.$$

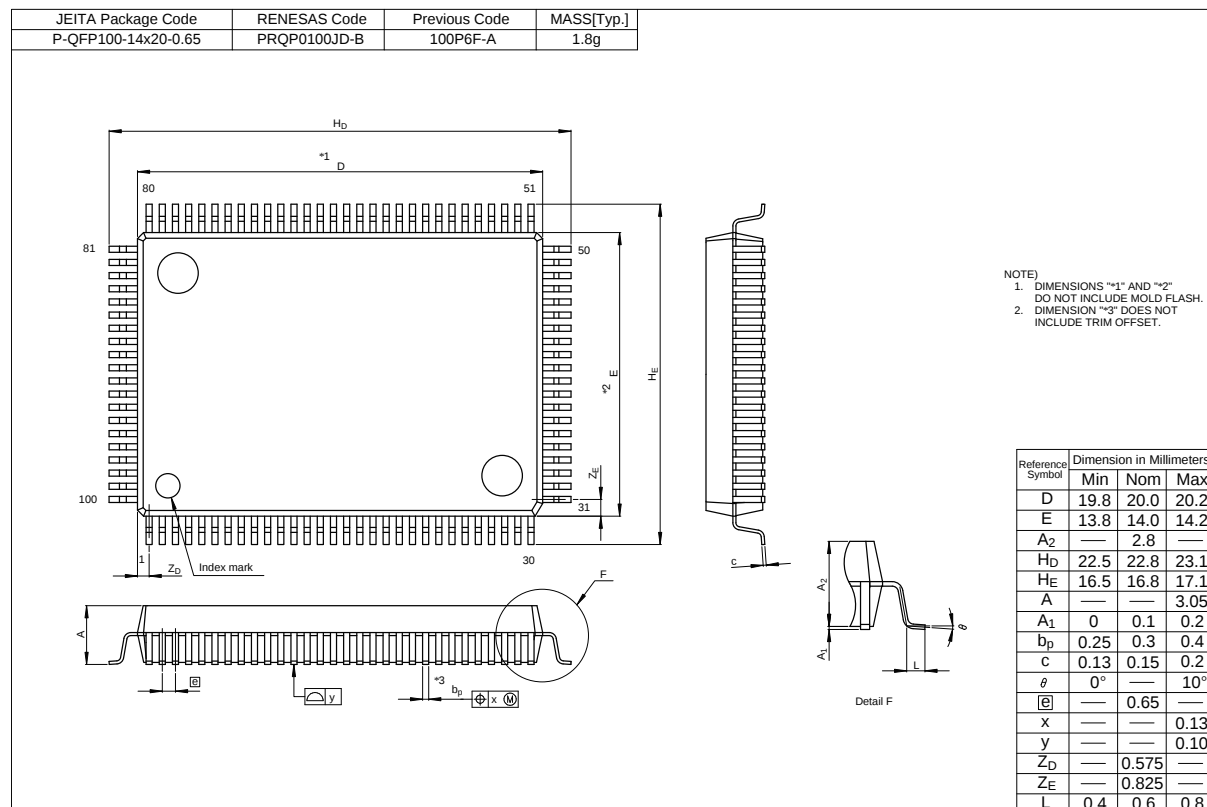
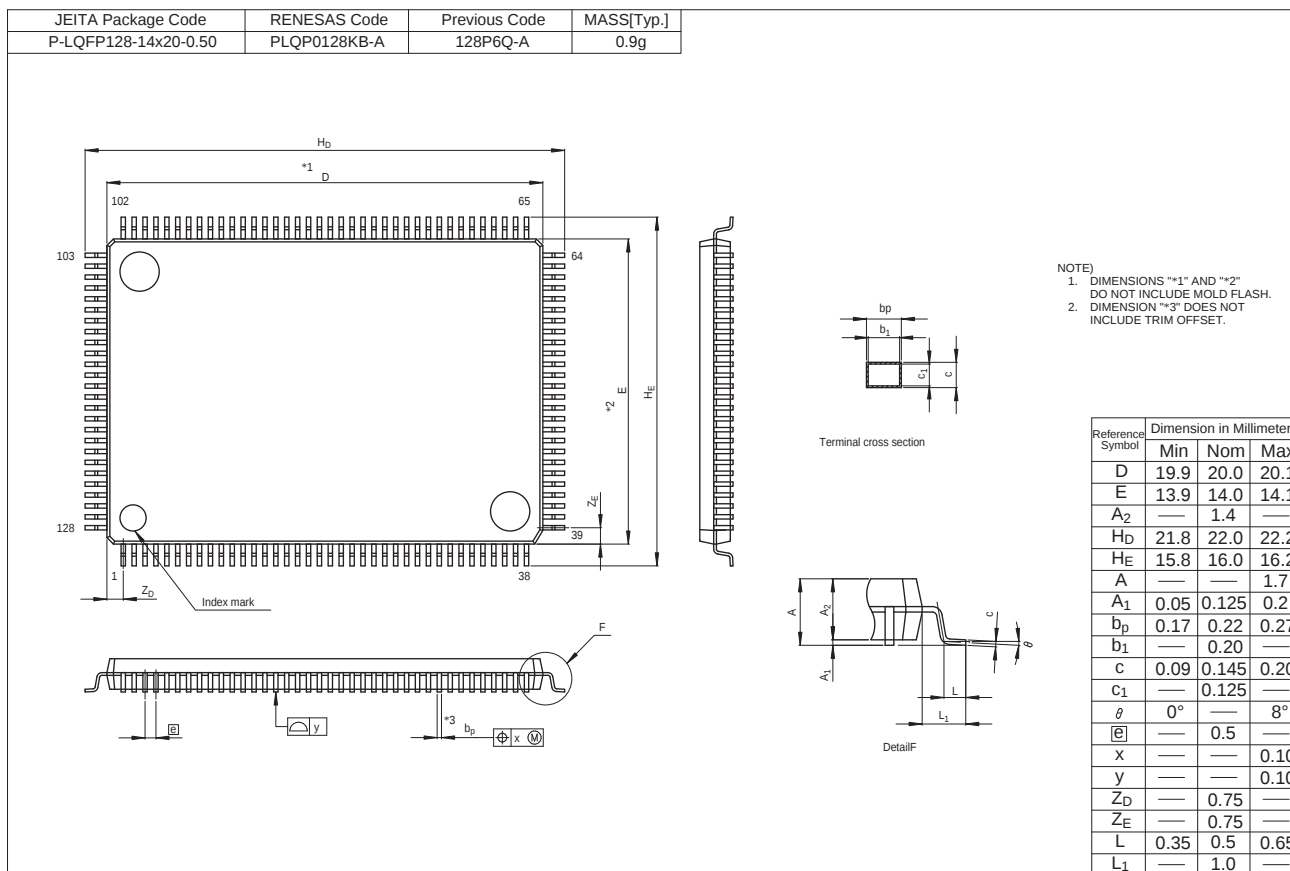


4. Calculated according to the BCLK frequency as follows: $\frac{0.5 \times 10^9}{f_{(BCLK)}} - 25[ns]$

Hold time is equal to or less than 0 ns when the BCLK frequency exceeds 20 MHz.

Appendix 1. Package Dimensions

The information on the latest package dimensions or packaging may be obtained from "Packages" on the Renesas Electronics website.



JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP100-14x14-0.50	PLQP0100KB-A	100P6Q-A / FP-100U / FP-100UV	0.6g

Top view of the PLQP0100KB-A package. Dimensions include H_0 (total height), D (pitch), E (width), H_1 (terminal height), and terminal numbers 1, 25, 51, 75, 76, 100. An index mark is shown. A detail F callout points to a specific terminal.

Side view of the PLQP0100KB-A package. Dimensions include H_0 (total height), H_1 (terminal height), and terminal numbers 1, 25, 51, 75, 76, 100.

Terminal cross section diagram. Dimensions include b_p (terminal width), b_1 (terminal thickness), c_1 (terminal height), and c (terminal pitch).

Detail F diagram. Dimensions include A (total height), A_0 (terminal height), A_1 (terminal width), L (terminal length), L_1 (terminal pitch), and c (terminal pitch).

NOTE)

- DIMENSIONS "1" AND "2"
- DO NOT INCLUDE MOLD FLASH.
- DIMENSION "3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeter			
	Min	Nom	Max	
D	13.9	14.0	14.1	
E	13.9	14.0	14.1	
A ₂	—	1.4	—	
H _D	15.8	16.0	16.2	
H _E	15.8	16.0	16.2	
A	—	—	1.7	
A ₁	0.05	0.1	0.15	
b _p	0.15	0.20	0.25	
b ₁	—	0.18	—	
c	0.09	0.145	0.20	
c ₁	—	0.125	—	
θ	0°	—	8°	
②	—	0.5	—	
x	—	—	0.08	
y	—	—	0.08	
Z _D	—	1.0	—	
Z _E	—	1.0	—	
L	0.35	0.5	0.65	
L ₁	—	1.0	—	